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(54) **MOUNTING APPARATUS FOR
COMPONENTS WITHOUT MOUNTING
POINTS IN MODULAR DATA CENTERS**

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(57) **ABSTRACT**

A modular data center includes: a modular information technology component (MITC), in which the MITC comprises a cooling distribution unit (CDU), a floor, a bottom cooling distribution unit mounting component (CDUMC), a modular over-rack component (MORC), and a top CDUMC, in which the floor comprises a floor track apparatus (FTA), in which the bottom CDUMC affixes the CDU to the FTA, in which the top CDUMC affixes the CDU to the MORC, in which the top CDUMC provides air containment with an internal environment of the MITC; and a modular environmental control component (MECC), in which the MECC comprises a plurality of environmental control components (ECCs) and built-in airflow connection components, in which the built-in airflow connection components remove and supply air to the MITC.

